

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6650817".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:25
L2	39	murali-venkatesan.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:26
L3	4	2 and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:26
L4	24	2 and (copper tin lead indium silver antimony)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:28
L5	6968	bump same pad same (indium tin lead silver antimony copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:28
L8	2	5 and (passive near align\$8) near12 (plate substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:29
S1	2	de-19810060-\$ did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/10 21:24
S5	825	385/52.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:03
S6	7	S5 and stack\$5 near12 (plan\$3 plate substrate surface) and ((solder near3 ball) bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:07
S7	2	"20040161201"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:05
S8	3	S5 and parallel near12 (plan\$3 plate substrate surface) same((solder near3 ball) bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:08
S9	27	(active passive) near3 alignment and parallel near12 (plan\$3 plate substrate surface) same((solder near3 ball) bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:08

S10	24	(active passive) near3 alignment and parallel near8 (plan\$3 plate substrate surface) same((solder near3 ball) bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:09
S11	21	(active passive) near3 alignment and parallel near3 (plan\$3 plate substrate surface) same((solder near3 ball) bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/06 17:09